

Title (en)

AN ELASTOMERIC FILM AND FIBER GRADE THERMOPLASTIC ELASTOMER COMPOSITION

Title (de)

ELASTOMERFILM UND FÜR DIE HERSTELLUNG VON FASERN GEEIGNETE, THERMOPLASTISCHE ELASTOMERZUSAMMENSETZUNG

Title (fr)

COMPOSITION ELASTOMERIQUE THERMOPLASTIQUE POUVANT ETRE EXTRUDEE EN FILMS ET FIBRES ELASTOMERIQUES

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Application

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Abstract (en)

[origin: WO0228965A1] In one embodiment, the present invention provides an elastomeric composition which is useful as an elastic film and fiber grade compound. These compositions contain at least one SEBS block copolymer having a vinyl content of 60 percent or greater and a molecular weight of 40,000 to 110,000 and a styrene block molecular weight of 5,000 to 15,000. The composition will comprise from 60 to 85 percent by weight of the block copolymer, from 5 to 25 percent by weight of a tackifying resin, and from 5 to 35 percent by weight of a low molecular weight, low density polyethylene. In a second embodiment of the present invention, an elastic film and fiber grade compound is provided which does not contain a tackifying resin. The composition is comprised of from 15 to 30 percent by weight of a low molecular weight, low density polyethylene and the balance is comprised of the block copolymer described above. A third embodiment of this invention provides another elastic film and fiber grade compound. This compound also contains no tackifying resin. It is comprised of from 2 to 60 percent by weight of a metallocene polyethylene elastomer polymer and the balance is the block copolymer described above.

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